

DATA SHEET

BTA212B series B
Three quadrant triacs
high commutation

Product specification

September 1997



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BTA212B series B

GENERAL DESCRIPTION

Glass passivated high commutation triacs in a plastic envelope suitable for surface mounting intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature, without the aid of a snubber.

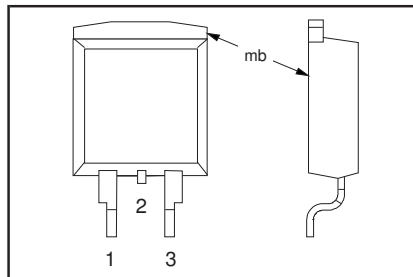
QUICK REFERENCE DATA

| SYMBOL | PARAMETER | MAX. | MAX. | MAX. | UNIT |
|--------------|---|--------------------|--------------------|--------------------|------|
| V_{DRM} | BTA212B- Repetitive peak off-state voltages | 500B 500 | 600B 600 | 800B 800 | V |
| $I_{T(RMS)}$ | RMS on-state current | 12 | 12 | 12 | A |
| I_{TSM} | Non-repetitive peak on-state current | 95 | 95 | 95 | A |

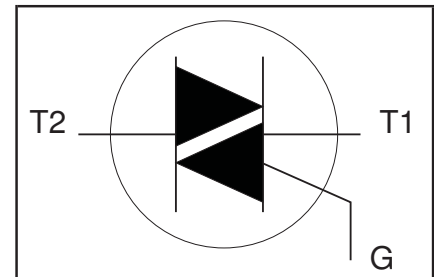
PINNING - SOT404

| PIN | DESCRIPTION |
|-----|-----------------|
| 1 | main terminal 1 |
| 2 | main terminal 2 |
| 3 | gate |
| mb | main terminal 2 |

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | | | UNIT |
|--------------|--|--|------|--------------------------|--------------------------|-------------|------------------|
| | | | | -500 500 ¹ | -600 600 ¹ | -800 800 | |
| V_{DRM} | Repetitive peak off-state voltages | | - | | | | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{mb} \leq 99^\circ\text{C}$ | - | 12 | | | A |
| I_{TSM} | Non-repetitive peak on-state current | full sine wave; $T_j = 25^\circ\text{C}$ prior to surge | - | 95 | | | A |
| I^2t | I^2t for fusing | $t = 20\text{ ms}$ | - | 105 | | | A ² s |
| dI_T/dt | Repetitive rate of rise of on-state current after triggering | $t = 10\text{ ms}$ | - | 45 | | | A/ μs |
| I_{GM} | Peak gate current | $I_{TM} = 20\text{ A}; I_G = 0.2\text{ A}; dI_G/dt = 0.2\text{ A}/\mu\text{s}$ | - | 100 | | | A |
| V_{GM} | Peak gate voltage | | - | 2 | | | V |
| P_{GM} | Peak gate power | | - | 5 | | | W |
| $P_{G(AV)}$ | Average gate power | over any 20 ms period | - | 0.5 | | | W |
| T_{stg} | Storage temperature | | -40 | 150 | | | $^\circ\text{C}$ |
| T_j | Operating junction temperature | | - | 125 | | | $^\circ\text{C}$ |

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/ μs .

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THERMAL RESISTANCES

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|----------------|---|---------------------------|------|------|------|------|
| $R_{th\ j-mb}$ | Thermal resistance junction to mounting base | full cycle | - | - | 1.5 | K/W |
| $R_{th\ j-a}$ | Thermal resistance junction to ambient | half cycle in free air | - | 60 | 2.0 | K/W |
| | | | - | - | - | K/W |

STATIC CHARACTERISTICS

 $T_j = 25\text{ °C}$ unless otherwise stated

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|----------|-----------------------------------|---|------|------|------|------|
| I_{GT} | Gate trigger current ² | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$ | | | | |
| | | T2+ G+ | 2 | 18 | 50 | mA |
| | | T2+ G- | 2 | 21 | 50 | mA |
| | | T2- G- | 2 | 34 | 50 | mA |
| I_L | Latching current | $V_D = 12\text{ V}$; $I_{GT} = 0.1\text{ A}$ | | | | |
| | | T2+ G+ | - | 31 | 60 | mA |
| | | T2+ G- | - | 34 | 90 | mA |
| | | T2- G- | - | 30 | 60 | mA |
| I_H | Holding current | $V_D = 12\text{ V}$; $I_{GT} = 0.1\text{ A}$ | - | 31 | 60 | mA |
| V_T | On-state voltage | $I_T = 17\text{ A}$ | - | 1.3 | 1.6 | V |
| V_{GT} | Gate trigger voltage | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$ | - | 0.7 | 1.5 | V |
| I_D | Off-state leakage current | $V_D = 400\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 125\text{ °C}$ | 0.25 | 0.4 | - | V |
| | | $V_D = V_{DRM(max)}$; $T_j = 125\text{ °C}$ | - | 0.1 | 0.5 | mA |

DYNAMIC CHARACTERISTICS

 $T_j = 25\text{ °C}$ unless otherwise stated

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---------------|---|--|------|------|------|------------|
| dV_D/dt | Critical rate of rise of off-state voltage | $V_{DM} = 67\% V_{DRM(max)}$; $T_j = 125\text{ °C}$; exponential waveform; gate open circuit | 1000 | 4000 | - | V/ μ s |
| dI_{com}/dt | Critical rate of change of commutating current | $V_{DM} = 400\text{ V}$; $T_j = 125\text{ °C}$; $I_{T(RMS)} = 12\text{ A}$; without snubber; gate open circuit | - | 24 | - | A/ms |
| t_{gt} | Gate controlled turn-on time | $I_{TM} = 12\text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 0.1\text{ A}$; $dI_G/dt = 5\text{ A}/\mu$ s | - | 2 | - | μ s |

² Device does not trigger in the T2-, G+ quadrant.

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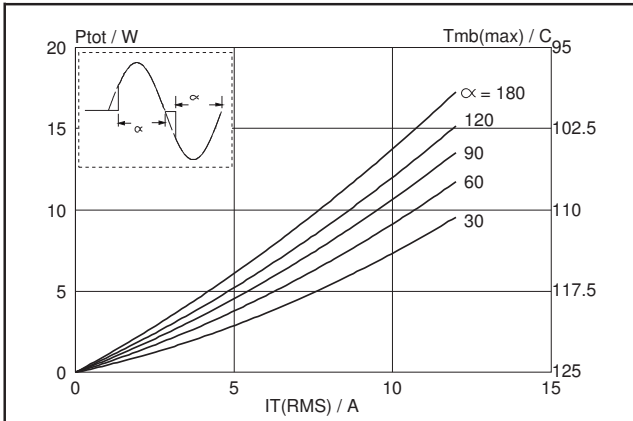


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

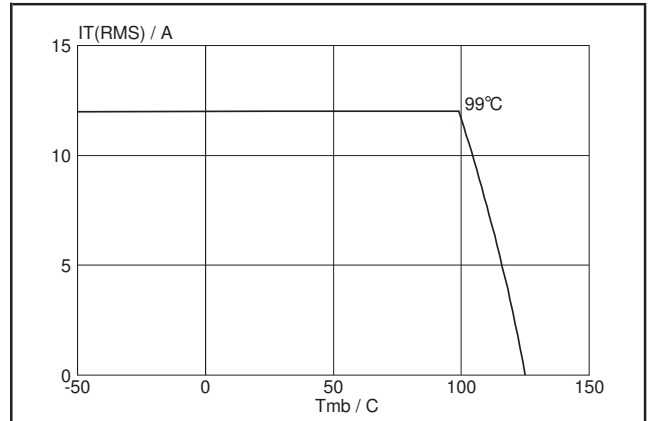


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb} .

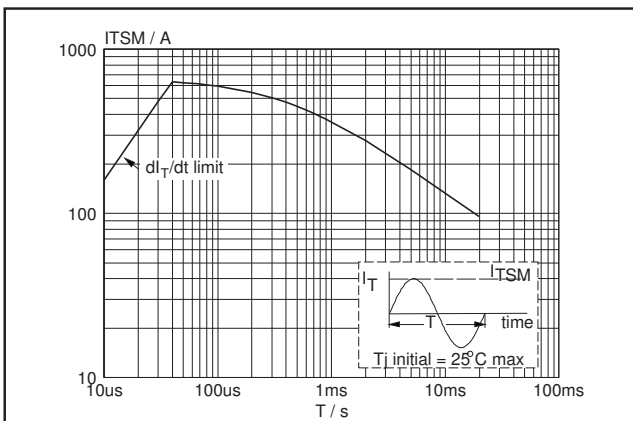


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \leq 20$ ms.

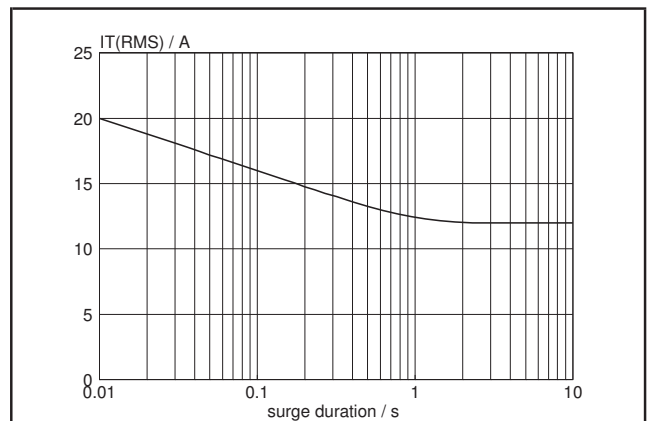


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, $f = 50$ Hz; $T_{mb} \leq 99$ °C.

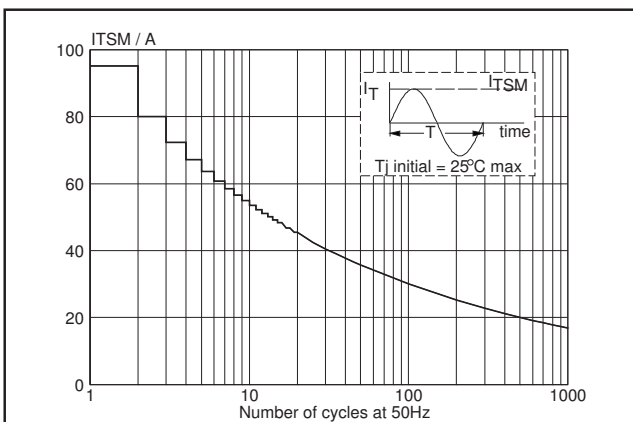


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, $f = 50$ Hz.

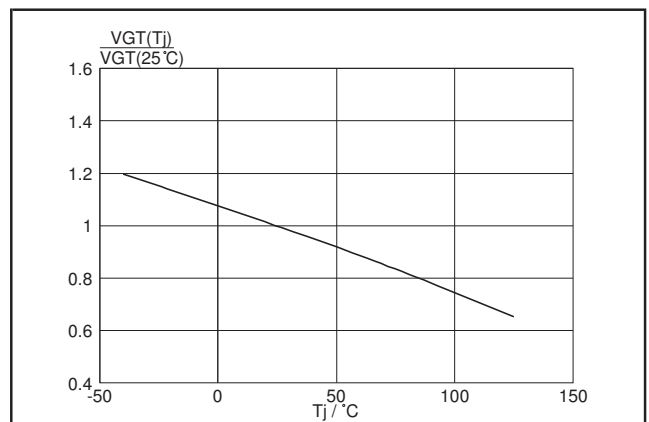
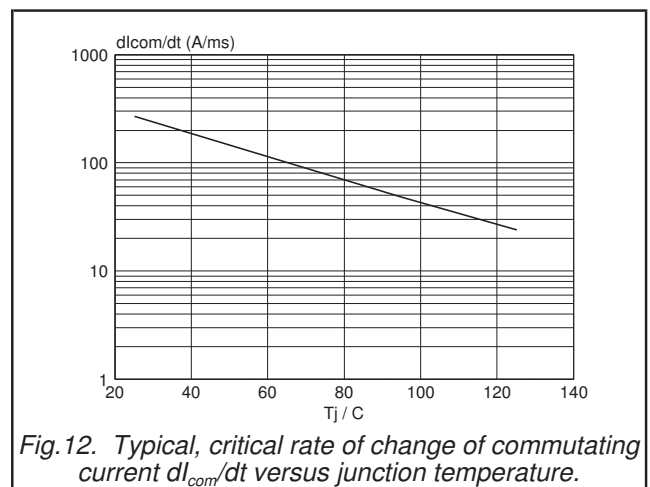
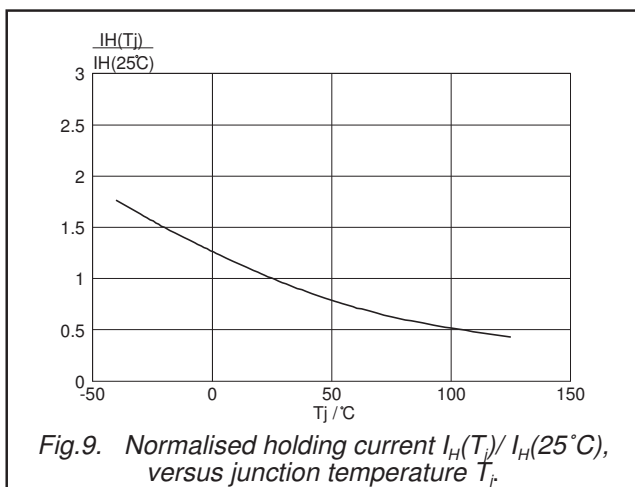
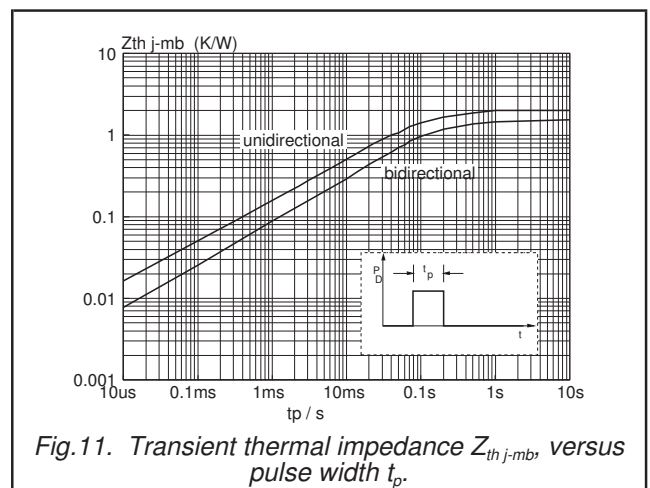
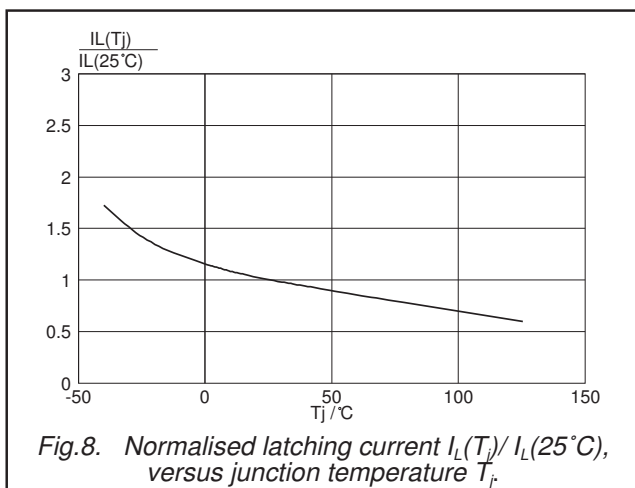
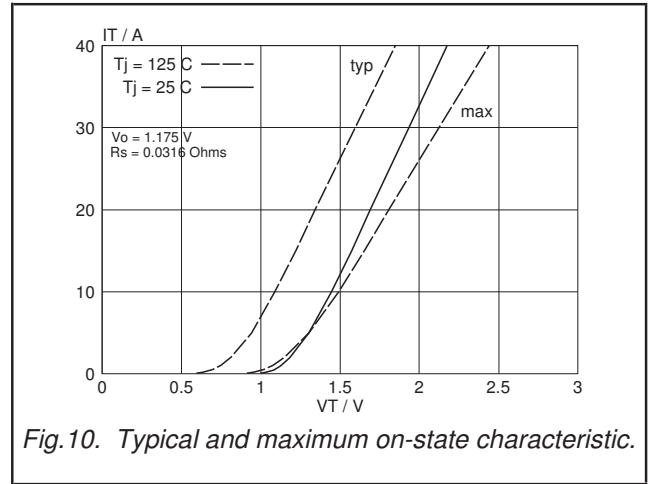
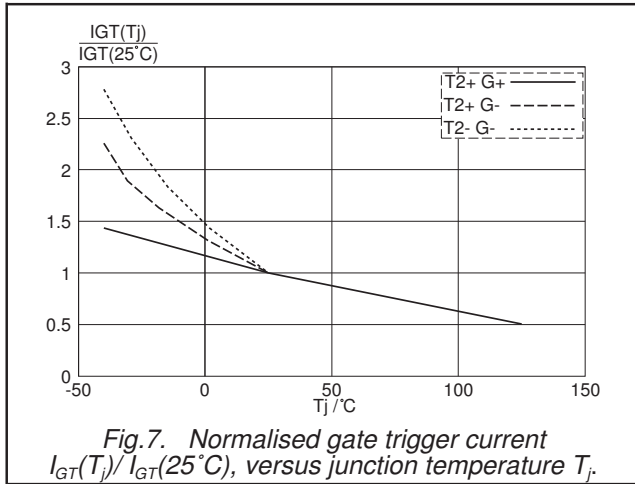


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j) / V_{GT}(25^\circ C)$, versus junction temperature T_j .

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MECHANICAL DATA

Dimensions in mm

Net Mass: 1.4 g

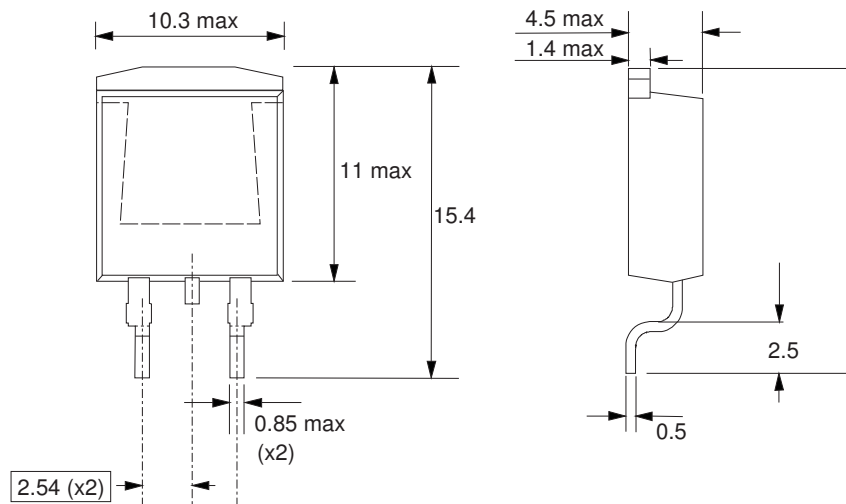


Fig.13. SOT404 : centre pin connected to mounting base.

Notes

1. Epoxy meets UL94 V0 at 1/8".

MOUNTING INSTRUCTIONS

Dimensions in mm

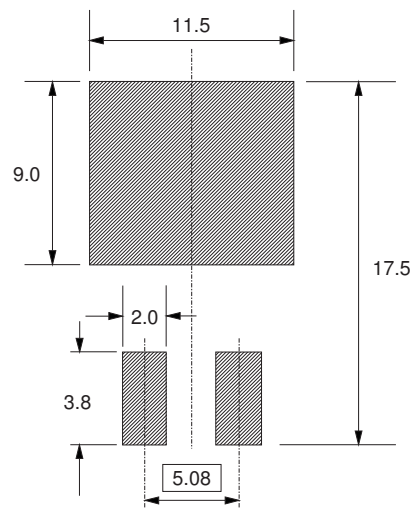


Fig.14. SOT404 : minimum pad sizes for surface mounting.

Notes

1. Plastic meets UL94 V0 at 1/8".

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DATA SHEET STATUS

| DOCUMENT STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾ | DEFINITION |
|--------------------------------|-------------------------------|---|
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| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

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